

FIG. 1

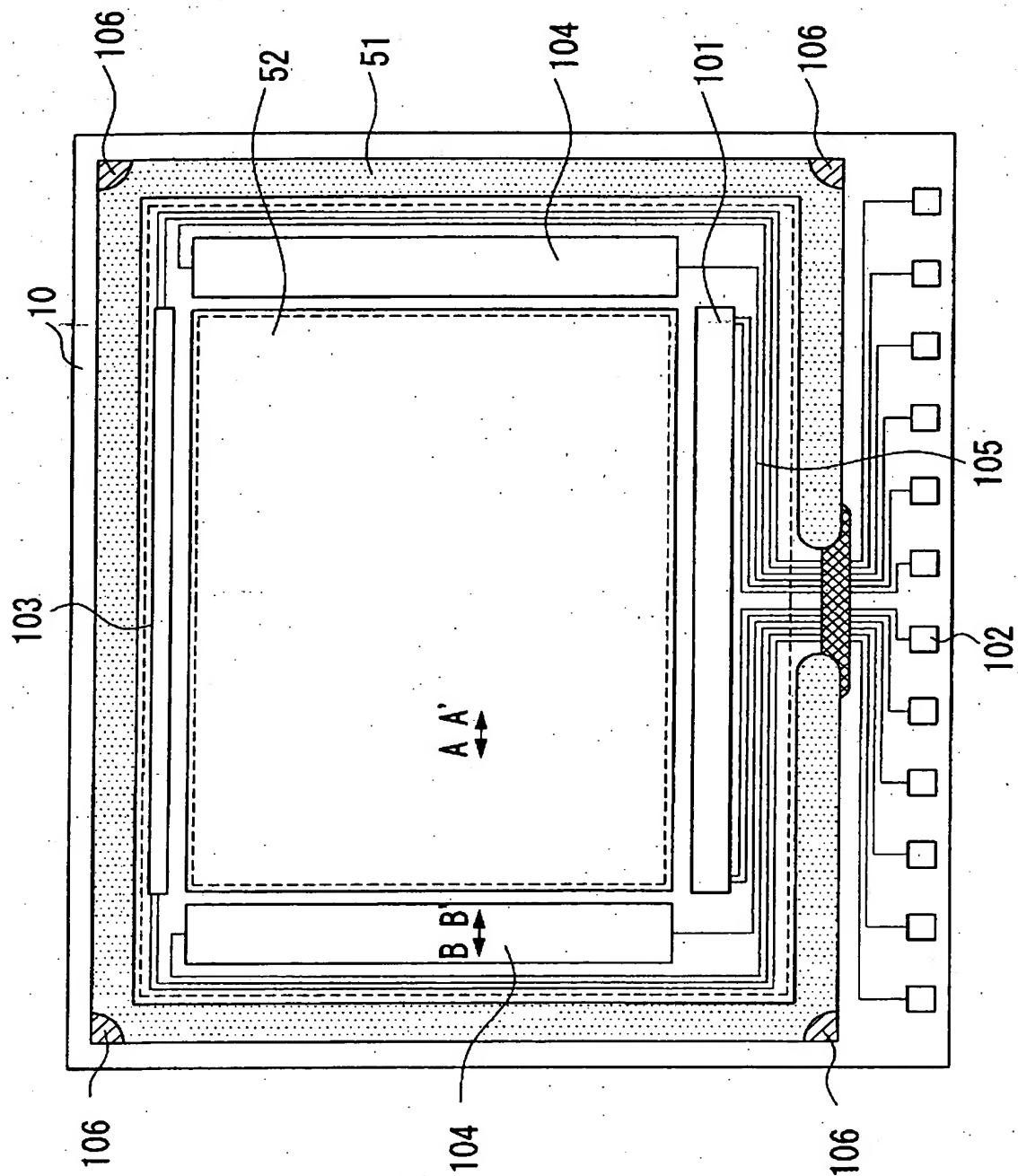


FIG. 2

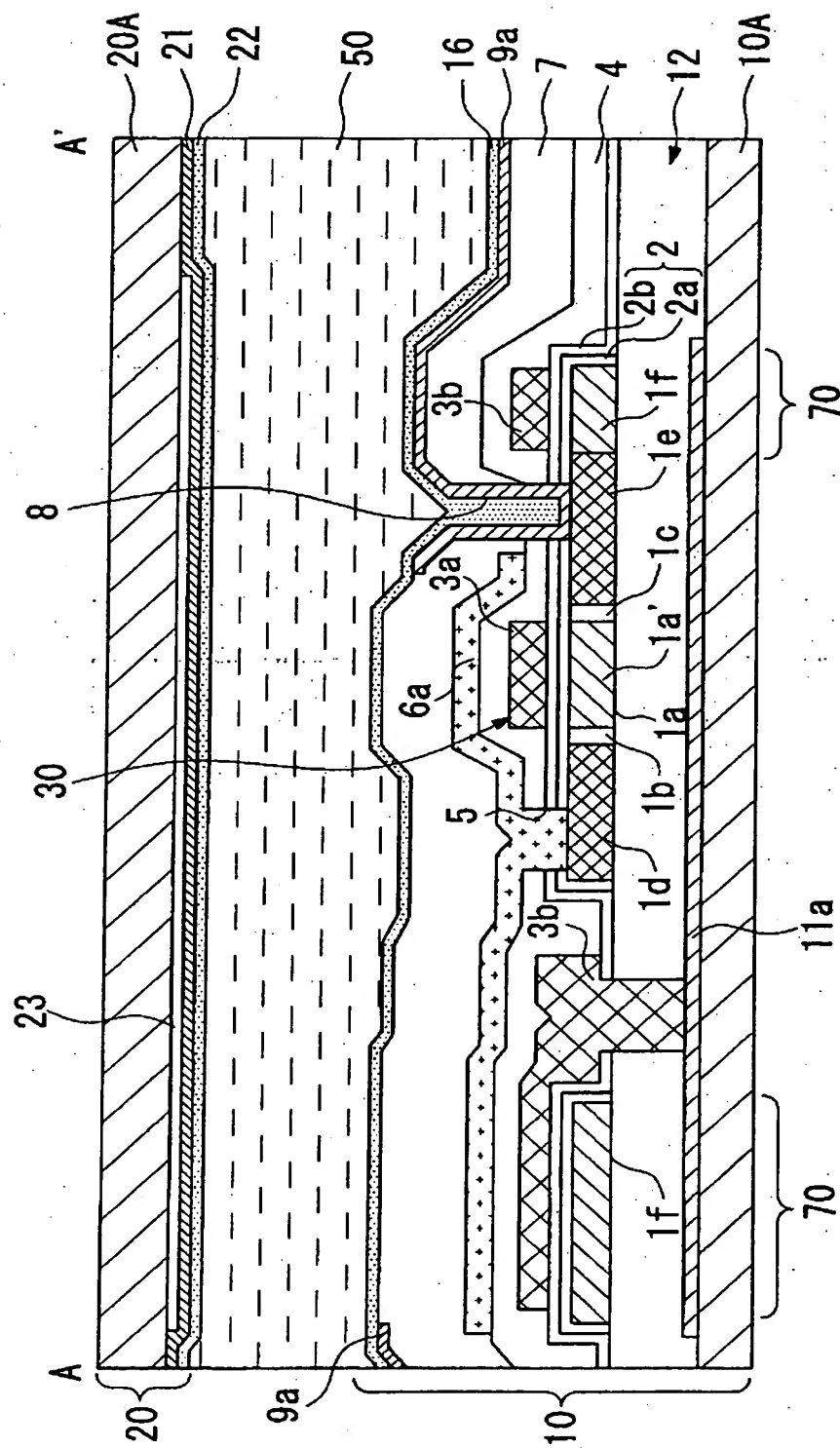


FIG. 3

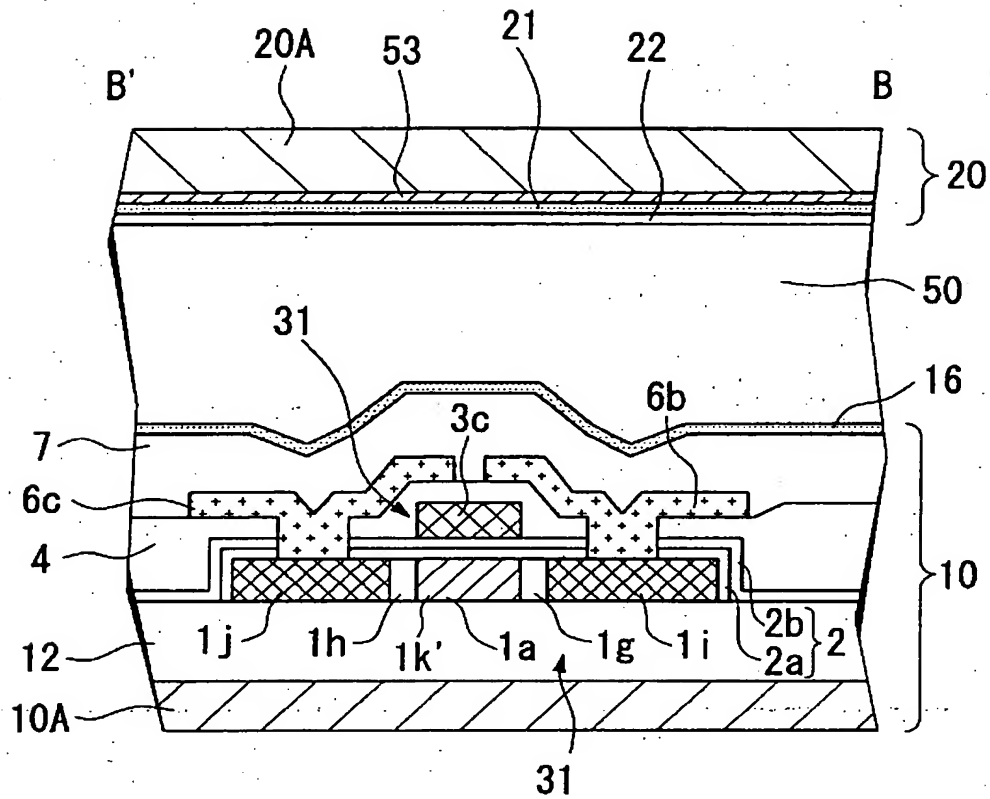


FIG. 4A

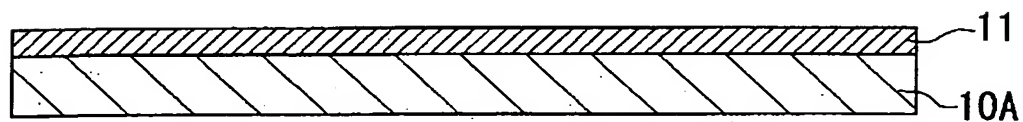


FIG. 4B

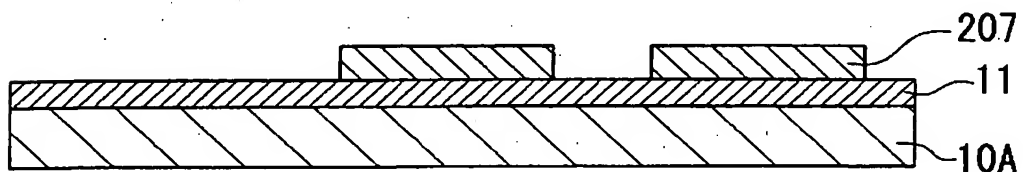


FIG. 4C

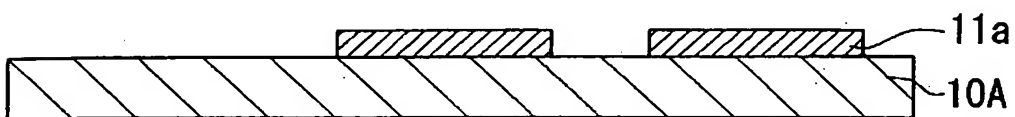


FIG. 5A

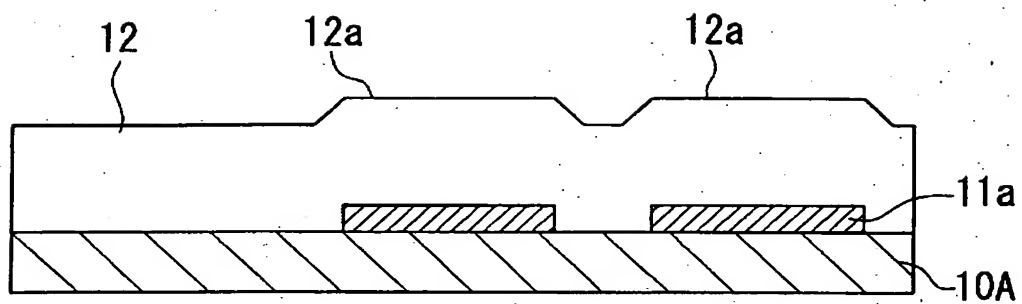
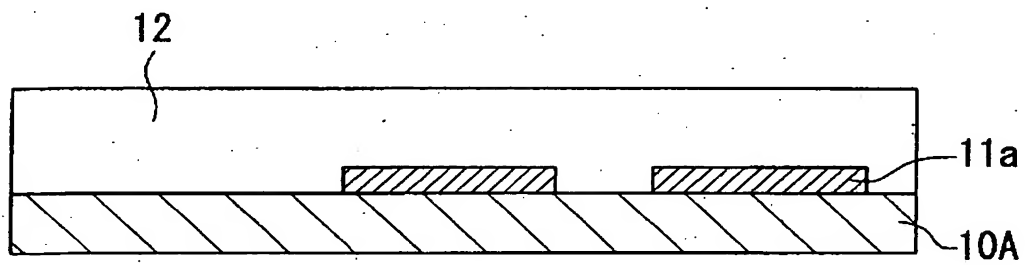


FIG. 5B



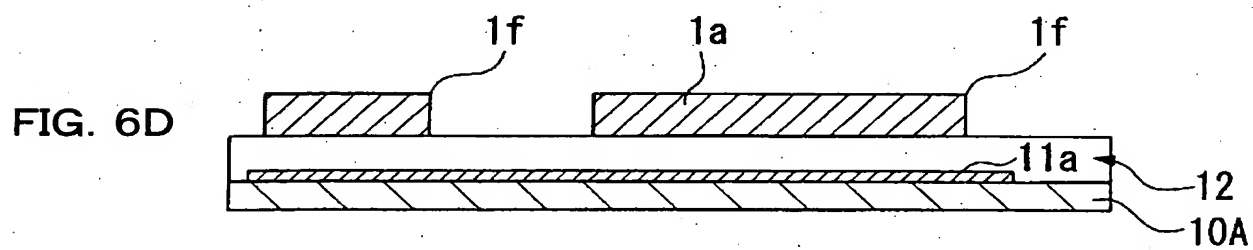
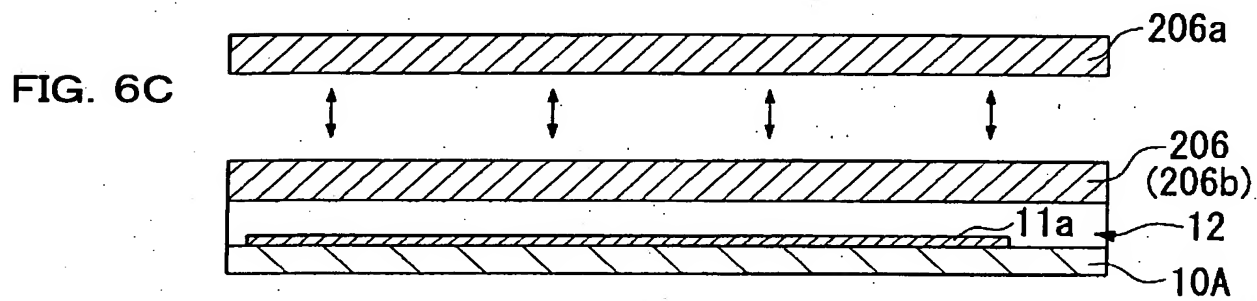
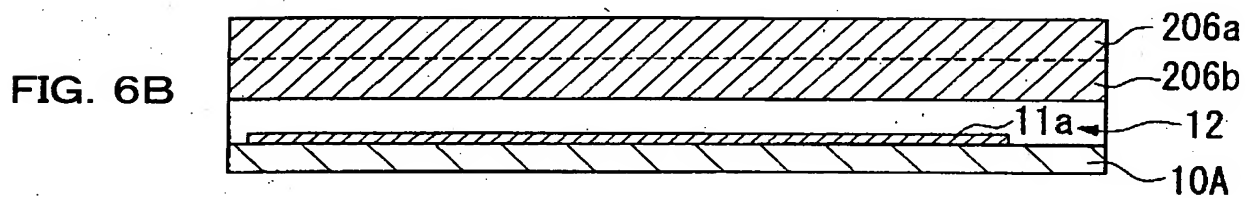
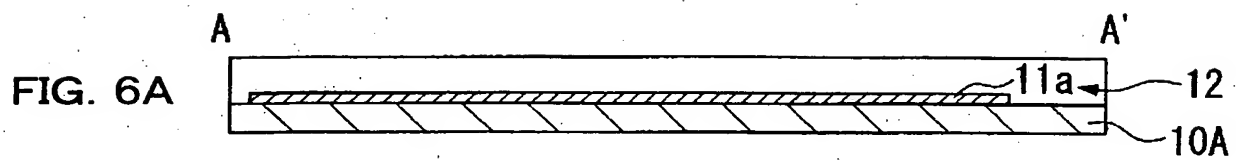


FIG. 7A

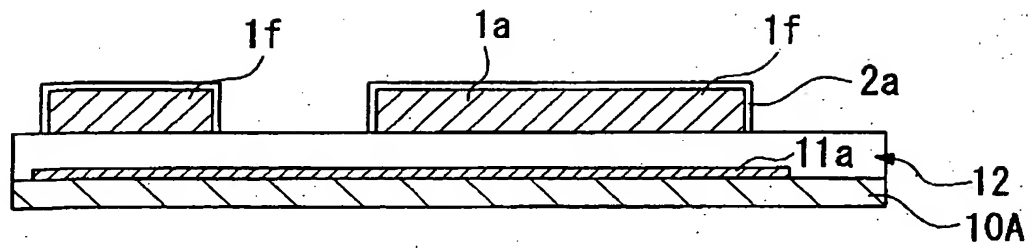


FIG. 7B

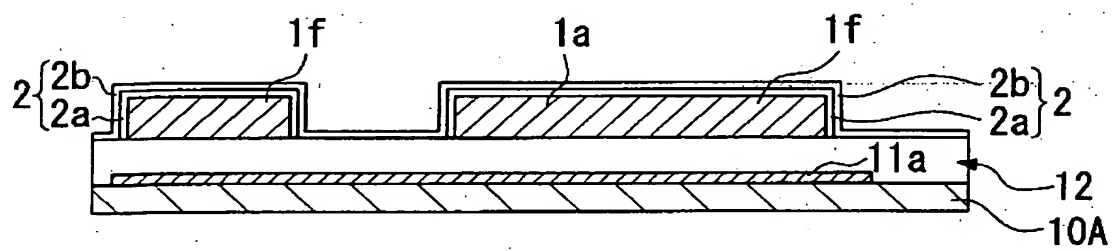


FIG. 8A

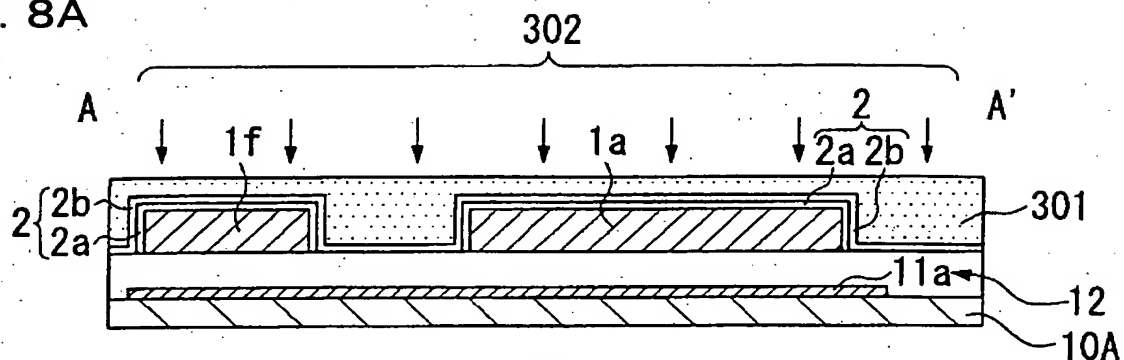


FIG. 8B

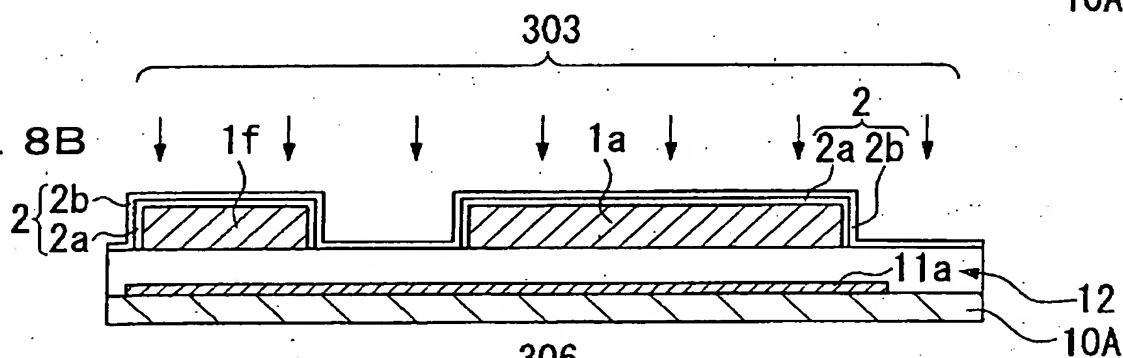


FIG. 8C

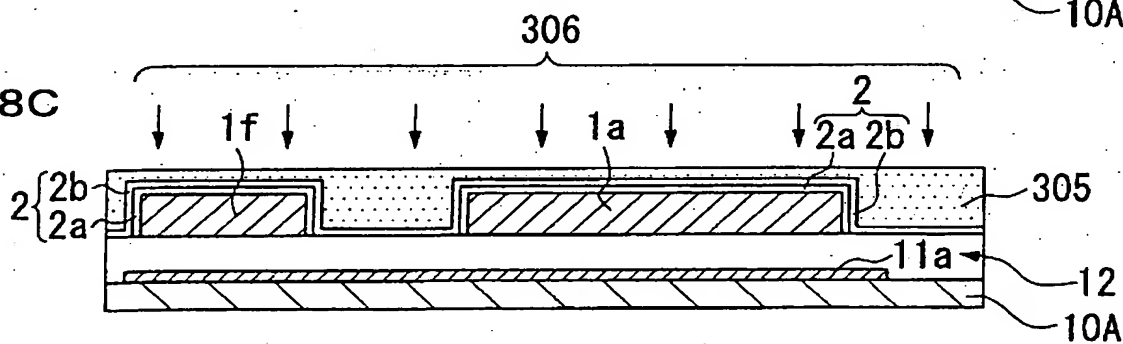


FIG. 8D

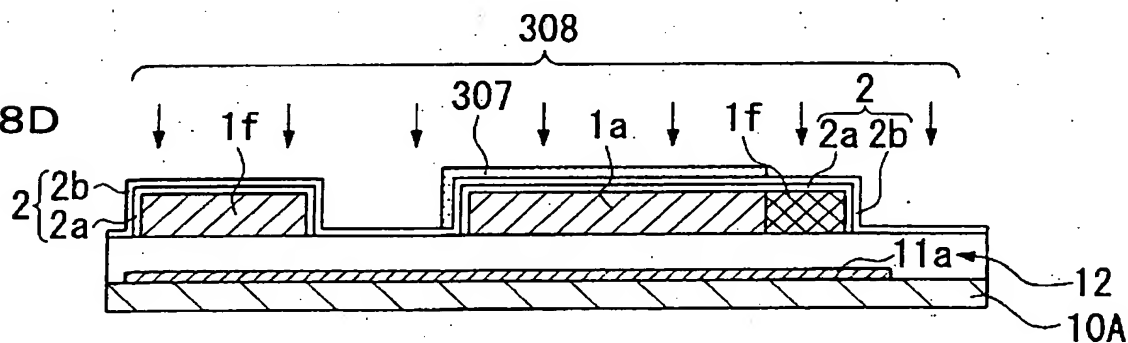


Figure 9A is a cross-sectional view of a semiconductor device 9A. It shows a substrate 10A with a thin layer 12 on top. A layer 2 is formed on the substrate, with a portion 11a exposed. A structure 13 is formed on the layer 2, consisting of a base 1a and a top layer 1f. A second structure 2 is formed on the first structure 13, with a portion 2a exposed. A cross-section A-A' is indicated.

[illegible][illegible][illegible]

FIG. 10A

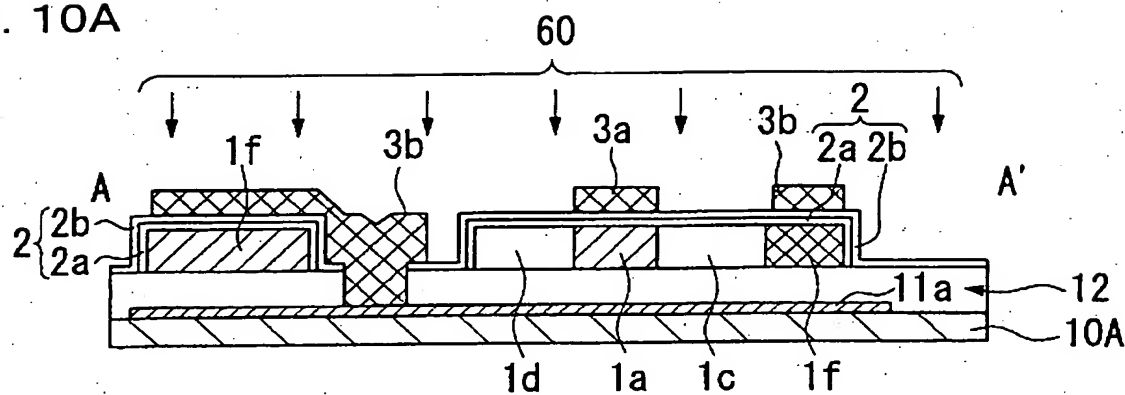


FIG. 10B

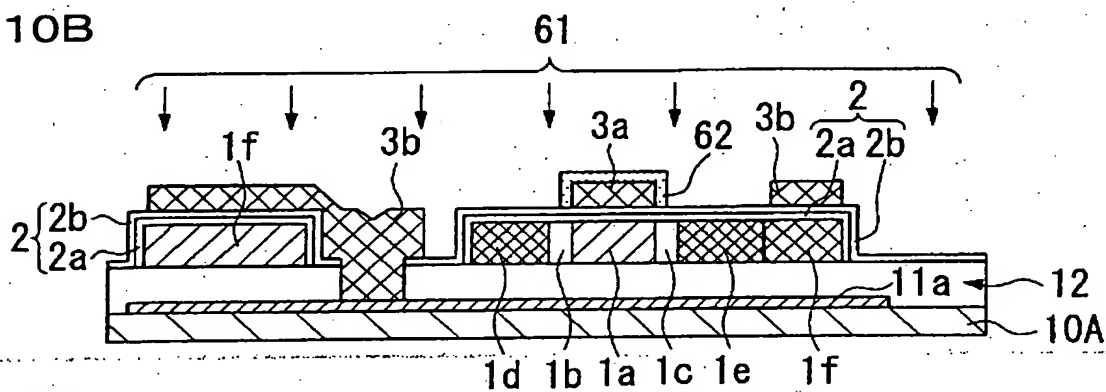


FIG. 10C

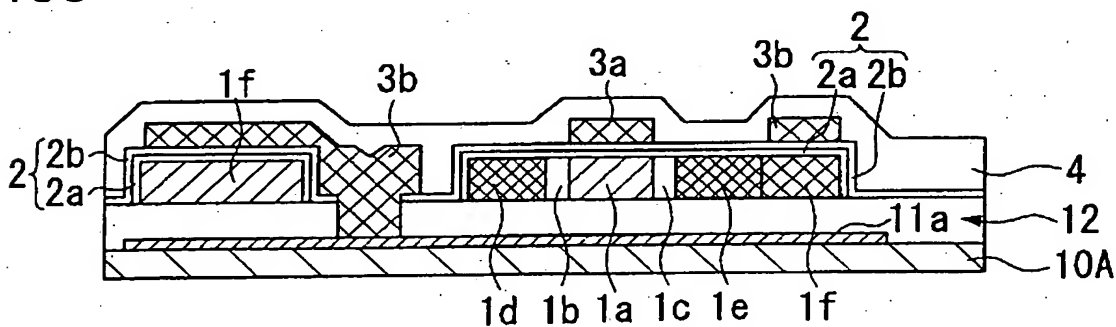


FIG. 10D

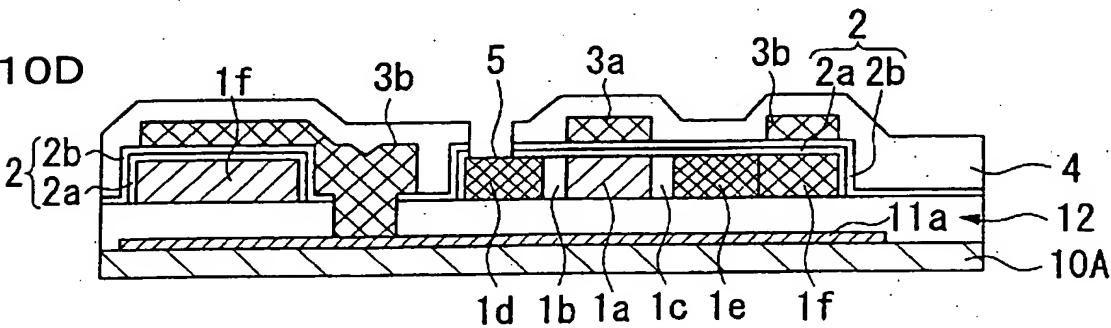


FIG. 11A

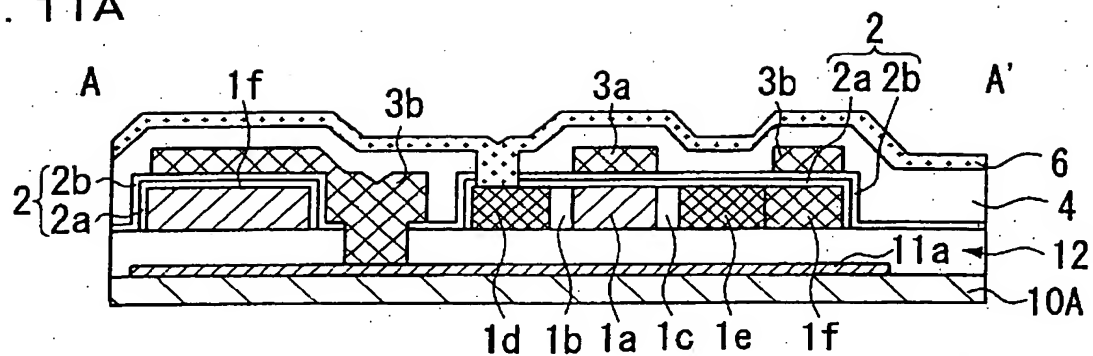


FIG. 11B

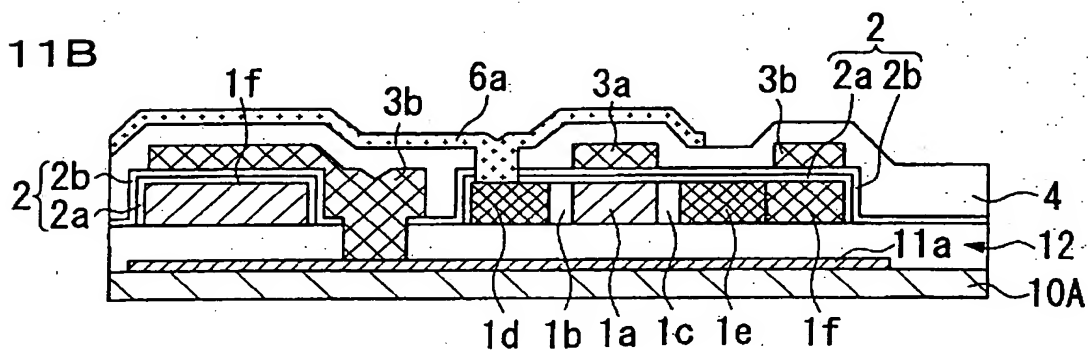
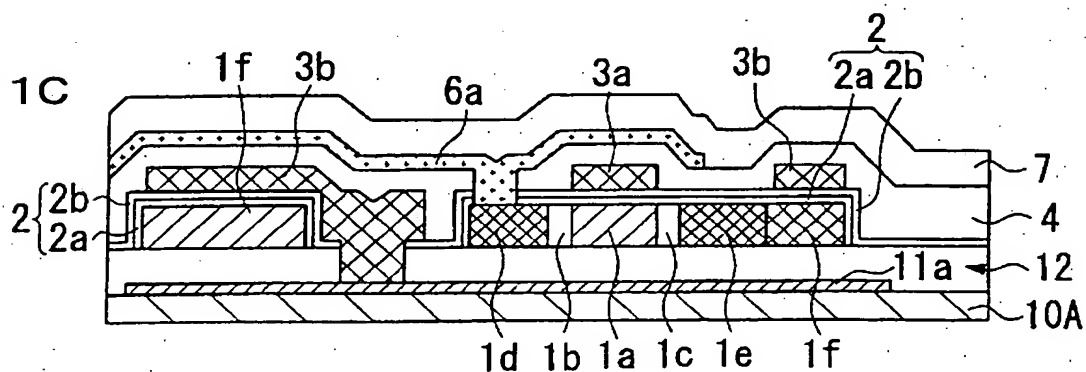
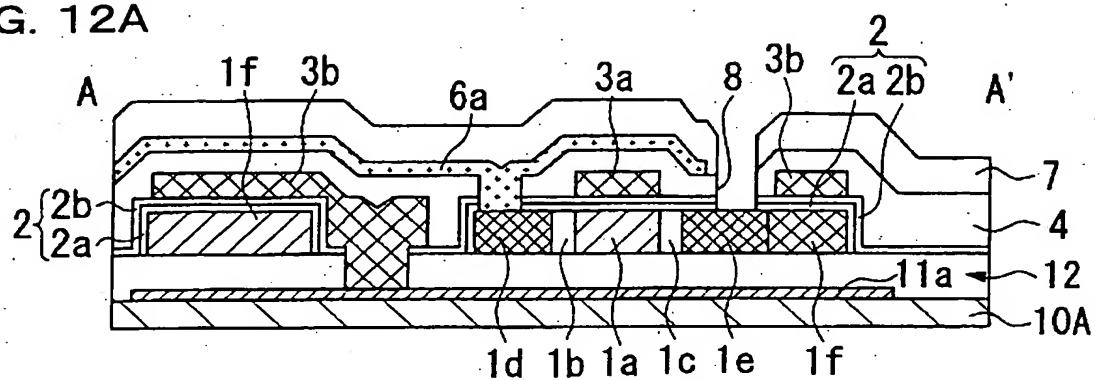


FIG. 11C





A detailed cross-sectional diagram of a semiconductor device. The base layer is labeled 10A. Above it are several horizontal layers: 11a, 12, 4, 7, and 9. A central vertical stack of layers is labeled 2, which includes sub-layers 2a and 2b. To the left of this stack is another vertical stack labeled 2B, also containing sub-layers 2a and 2b. Various other components are labeled: 1f, 3b, 6a, 3a, 3b, 1d, 1b, 1a, 1c, 1e, 1f, and 11a. The diagram shows different materials represented by various hatching patterns.

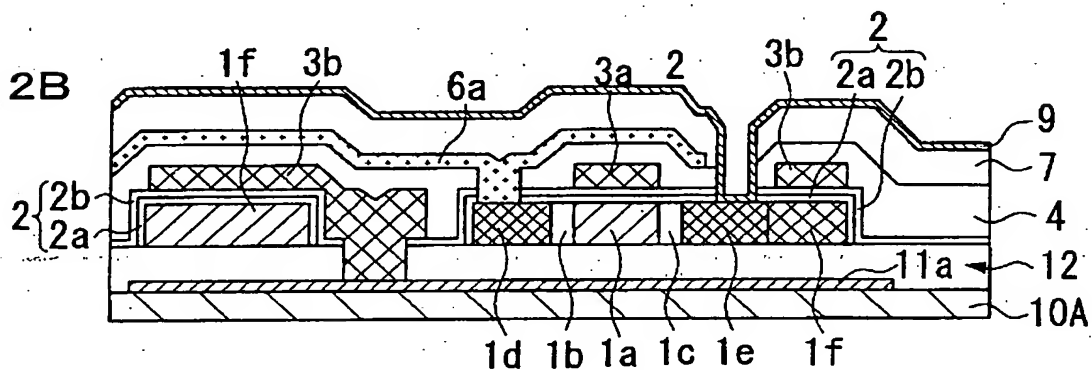


Fig. 2C is a cross-sectional view of the semiconductor device. It shows a substrate 10A with a base layer 12 and a thin layer 11a. A series of layers are deposited on top: 1f, 3b, 6a, 3a, 3b, 2 (comprising 2a and 2b), 9a, 7, 4, and 10A. The device features a central region with a cross-hatched pattern, likely representing a semiconductor layer, and is surrounded by various conductive and insulating layers. The labels 1d, 1b, 1a, 1c, 1e, and 1f indicate specific regions or layers within the device structure.

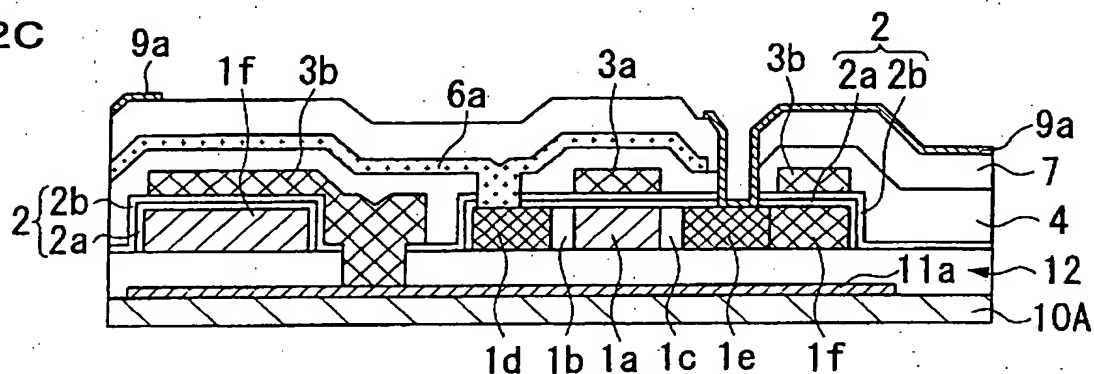


FIG. 13A

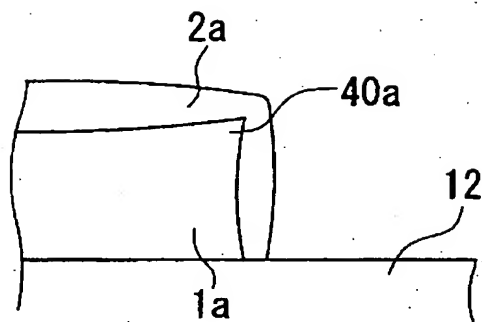


FIG. 13B

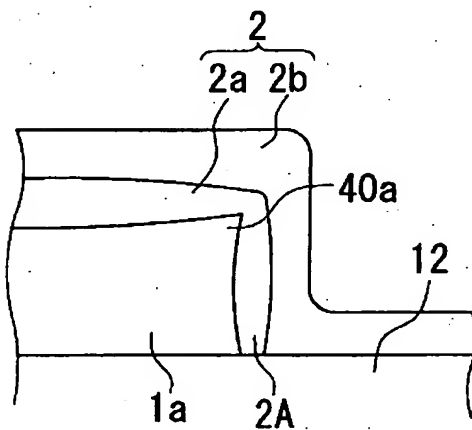


FIG. 14

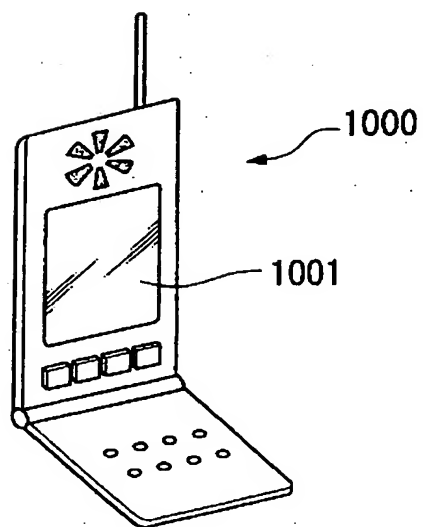


FIG. 15

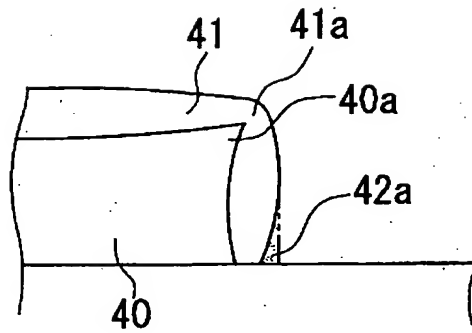


FIG. 16

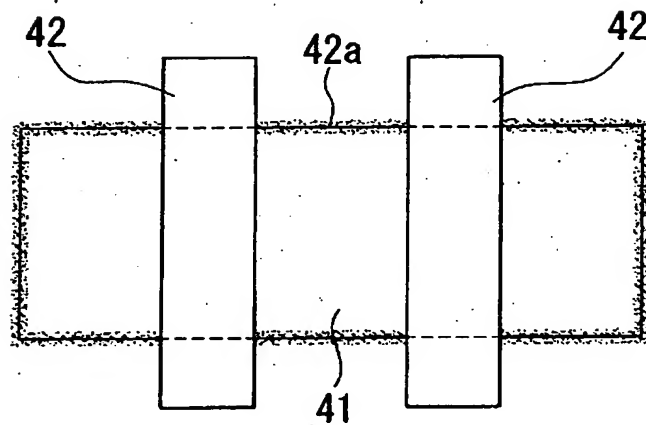


FIG. 17

